Plaskon ALP-2 (188)

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is an epoxy encapsulant for high productivity packaging of very thin, stress-sensitive devices such as TSSOP's. Performance attributes are intended to meet or exceed JEDEC Level 1 for all packages and have no or limited post-mold cure, fast cure cycle times tailored to specific applications and excellent adhesion to Cu and Pd-Ni leadframes.

General Information			
Features	Semi-conductive		
	Low hygroscopicity		
	Laser marking		
	Fast molding cycle		
	Fast curing		
	Good formability		
Uses	Thin wall packaging		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity	1.92	g/cm³	ASTM D792
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Flexural Modulus			ASTM D790
22°C	2.26	MPa	ASTM D790
260°C	0.0735	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.0127	MPa	ASTM D790
260°C	6.86E-4	MPa	ASTM D790
Thermal	**Nominal Value**	**Unit**	**Test Method**
Glass Transition Temperature	111	°C	ASTM E1356
CLTE - Flow	9.0E-6	cm/cm/°C	ASTM D696
Thermal Conductivity	1.0	W/m/K	ASTM C177
Electrical	**Nominal Value**	**Unit**	**Test Method**
Volume Resistivity	1.0E+12	ohms·cm	ASTM D257
Dielectric Strength	55	kV/mm	ASTM D149
Dielectric Constant (1 MHz)	3.80		ASTM D150
Flammability	**Nominal Value**	**Unit**	**Test Method**
Flame Rating (3.18 mm)	V-0		UL 94
Additional Information			

Recommended Storage Temperature: <5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 6 monthsLife @ 22°C, defined as not more than 40% loss of spiral flow based on original values.: 2 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 0.5 daysSpiral Flow, 175°C, 1000 psi: 100 cmShimadzu Viscosity, 175°C, 1000 psi: 50 poiseRam Follower Gel Time, 175°C, 1000 psi: 16 secAsh Content: 86 %Hydrolyzable Halides: <1 ppmMoisture Absorption, 85°C/85%RH, 168 hrs: 0.25%Cull Hot Hardness, Shore D: 70Volume Resistivity, 22°C: 1e12 ohm-cmVolume Resistivity, 150°C: 1e9 ohm-cmAll test specimens are transfer molded and post cured for 4 hours at 175°C
Linear Thermal Expansion, Alpha 1: 9 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 39 cm^-6/cm/°C

Injection instructions

Resin Transfer Molding:
Molding Temperature: 170 to 185°C
Molding Pressure: 750 to 1250 psi
In Mold Cure Time: 70 to 120 sec
Post Mold Cure Time, 175°C: 0 to 4 hr

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